



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



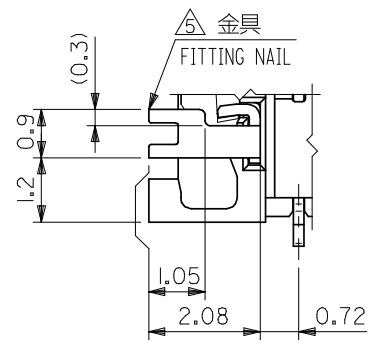
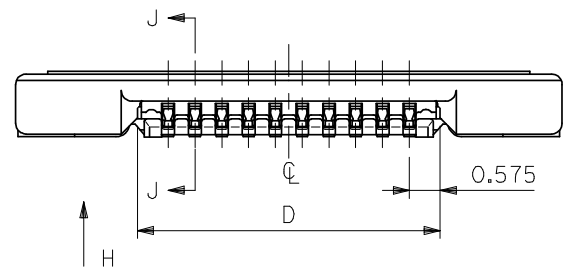
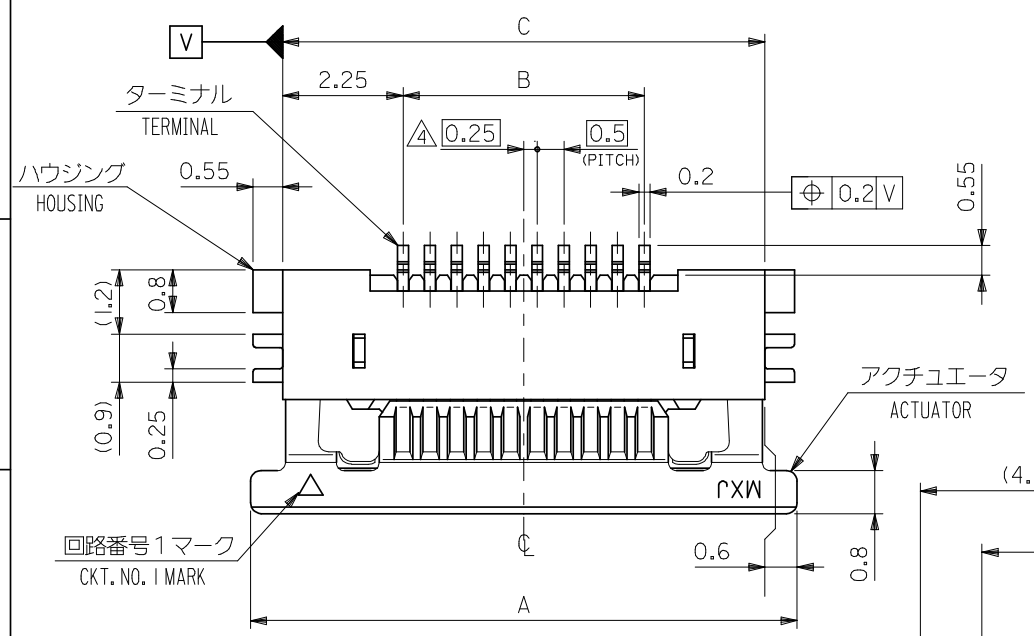
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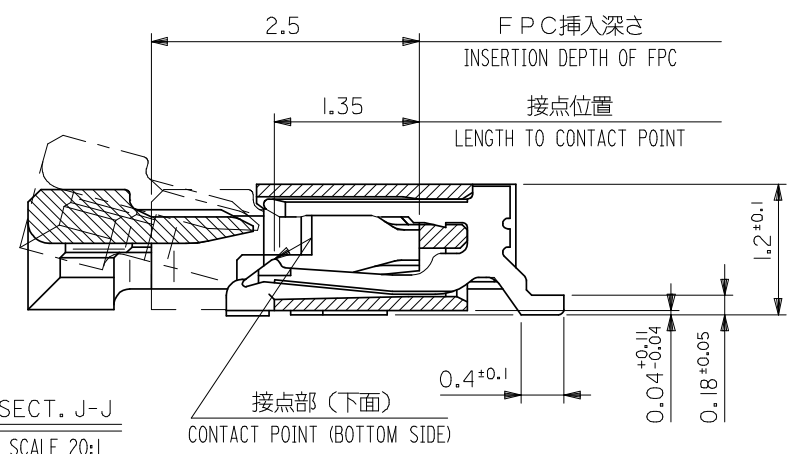
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

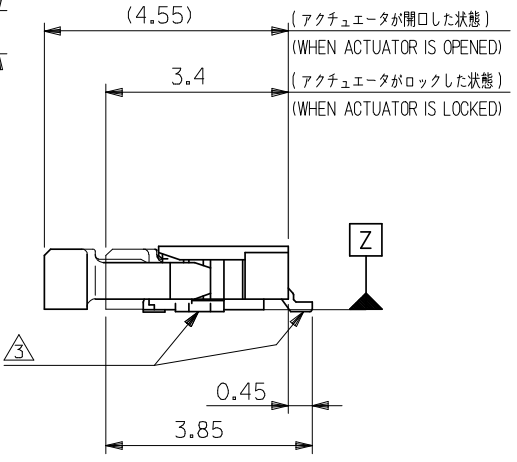




VIEW H

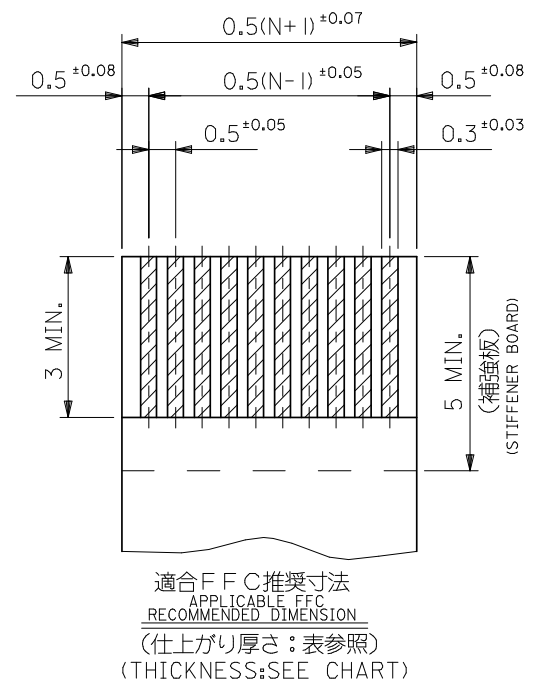
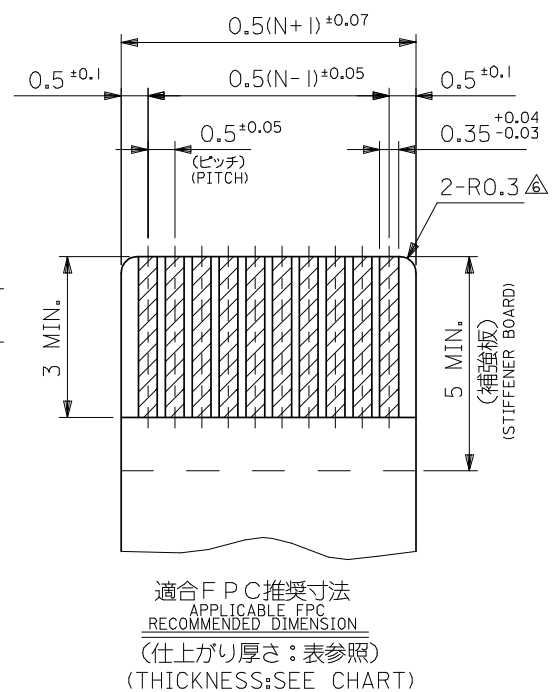
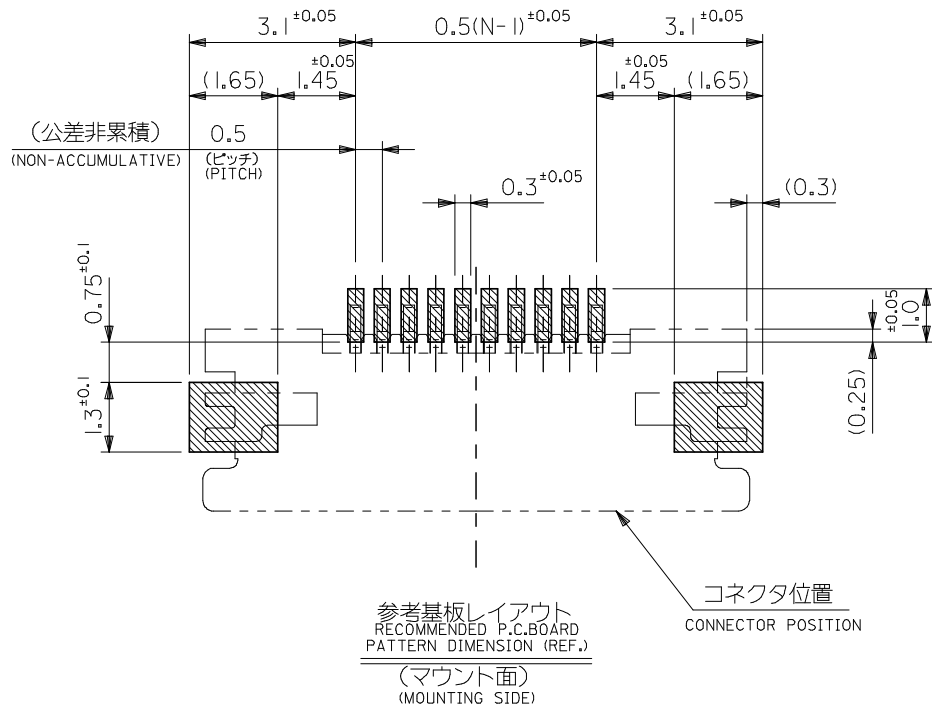


SECT. J-J
SCALE 20:1



0.28±0.03	13.65	17.0	12.5	18.2	54548-2671	54548-2629	26
	12.65	16.0	11.5	17.2	54548-2471	54548-2429	24
	12.15	15.5	11.0	16.7	54548-2371	54548-2329	23
	11.65	15.0	10.5	16.2	54548-2271	54548-2229	22
	11.15	14.5	10.0	15.7	54548-2171	54548-2129	21
	10.65	14.0	9.5	15.2	54548-2071	54548-2029	20
	10.15	13.5	9.0	14.7	54548-1971	54548-1929	19
	9.65	13.0	8.5	14.2	54548-1871	54548-1829	18
	9.15	12.5	8.0	13.7	54548-1771	54548-1729	17
	8.65	12.0	7.5	13.2	54548-1671	54548-1629	16
	8.15	11.5	7.0	12.7	54548-1571	54548-1529	15
	7.65	11.0	6.5	12.2	54548-1471	54548-1429	14
	0.3±0.03	7.15	10.5	6.0	11.7	54548-1371	54548-1329
	6.65	10.0	5.5	11.2	54548-1271	54548-1229	12
	6.15	9.5	5.0	10.7	54548-1171	54548-1129	11
	5.65	9.0	4.5	10.2	54548-1071	54548-1029	10
	5.15	8.5	4.0	9.7	54548-0971	54548-0929	9
	4.65	8.0	3.5	9.2	54548-0871	54548-0829	8
	4.15	7.5	3.0	8.7	54548-0771	54548-0729	7
	3.65	7.0	2.5	8.2	54548-0671	54548-0629	6
	3.15	6.5	2.0	7.7	54548-0571	54548-0529	5
	2.65	6.0	1.5	7.2	54548-0471	54548-0429	4
FPC THICKNESS	D	C	B	A	EMBOSSED TAPE ORDER No. オータ-番別	製品番号 MATERIAL No.	極数 Ck+

REVISED EC NO: J2008-4048 2008/06/13 DRWN:MNABEI 2008/06/16 CH'KD:THARUYAMA 2008/06/16 APPR:NUKITA 2008/06/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
			MM ONLY	10:1	METRIC			
	10 UNDER	±0.2	DRAWN BY	DATE	TITLE			
	10 OVER 30 UNDER	±0.25	HSHIMABUKURO	'04/02/10	0.5 FPC CONN ZIF HSG ASSY FOR SMT RA BTM CONT -LEAD FREE-			
	30 OVER	±0.3	KTOJO	'04/02/10				
ANGULAR ±3 °		APPROVED BY	DATE	MOLEX INCORPORATED				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MSASAO	'04/02/10	MATERIAL NO.	DOCUMENT NO.	SHEET NO.		
		SEE TABLE		SD-54548-039	1 OF 2			
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								



FPC/FFC について:
打ち抜き方向は導体側から補強板側を推奨します。
導体部については軟銅箔35μmまたは50μmを推奨します。

ABOUT FPC/FFC
RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED CONDUCTOR SPEC :
THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER.

FPC について:
補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。
接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。

ABOUT FPC
RECOMMENDED MATERIAL/THICKNESS.
STIFFENER FILM : POLYIMIDE
BASE FILM THICKNESS : 25μm
BONDING AGENT : THERMOSETTING BONDING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON THE CONTACT AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE THE DEFECT IN ELECTRICAL CONTINUITY.

注記 NOTES

- I. 使用材料 MATERIAL
- ハウジング : LCP, UL94V-0
HOUSING
- アクチュエータ : PPS, UL94V-0
ACTUATOR
- ターミナル :リン青銅 (t=0.2)
TERMINAL PHOSPOR BRONZE
- メッキ : 接点部:金メッキ
PLATING CONTACT PORTION : GOLD PLATING
- テール部:錫メッキ
SOLDERING PORTION : TIN OVER PLATING
- 下地:ニッケルメッキ
UNDER PLATING:NICKEL PLATING
- 金具 :リン青銅、錫メッキ (t=0.2)
FITTING NAIL PHOSPOR BRONZE, TIN PLATING
- 下地:ニッケルメッキ
UNDER PLATING:NICKEL PLATING

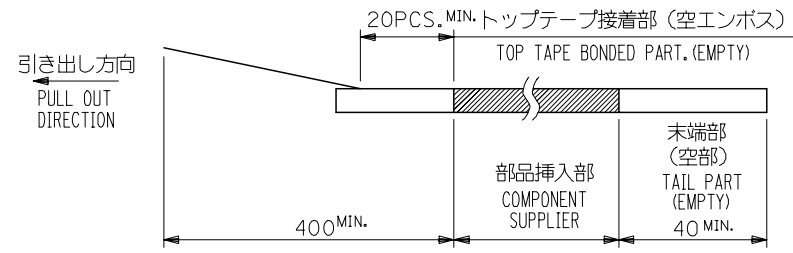
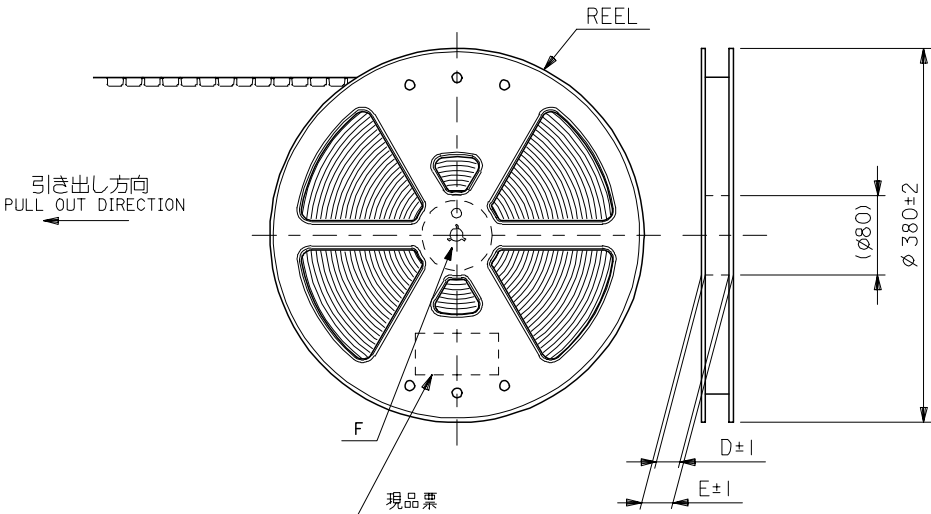
- △パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.
- △RO.3はFPC導体部にかからないこと
RO.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.
- 7.本製品は54548-**21の鉛フリー(部分金メッキ)品である。
THIS PRODUCT IS LEAD FREE OF 54548-**21 (SELECTIVE GOLD).
8. N: 極数 N: CIRCUIT.

2. エンボステップ梱包時は、アクチュエータがロックした状態とする。
IN THE PACKAGE,ACTUATOR OF PART NO.54548-**29 SHOULD BE LOCKED.
- △ソルダーテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 Z に対し上方向 OMAX.、下方向 O.15MAX.とし
相互のバラツキ量はO.1MAX.とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM Z
UPPER DIRECTION: O MAX. , LOWER DIRECTION: O.15 MAX.
OFFSET BETWEEN UPPER AND LOWER O.1 MAX.
- △偶数極に適用。
APPLY FOR EVEN CIRCUIT.

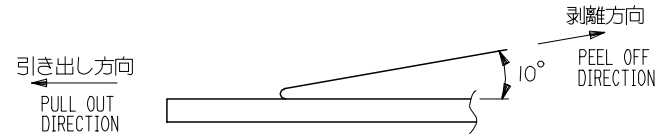
REVISED EC NO: J2008-4048 DRWN:WABEI 2008/06/13 CHKD:THARYAMA 2008/06/16 APPR:NUKITA 2008/06/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	MODEL No. 54548-**29	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY HSHIMABUKURO	DATE '04/02/10	TITLE 0.5 FPC CONN ZIF HSG ASSY FOR SMT RA BTM CONT -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE '04/02/10	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY MSASAO	DATE '04/02/10	DOCUMENT NO. SD-54548-039		
	ANGULAR ±3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE SHEET 1	SHEET NO. 2 OF 2			
			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

NOTES

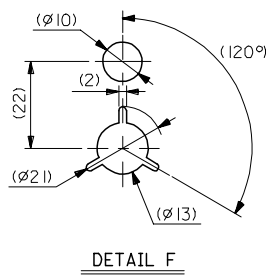
- 製品詳細寸法については図面 SD-54548-039 を参照下さい。
RE DETAILED DIMENSION, SEE SD-54548-039
- 梱包数量：3000個/リール
NUMBER OF CONNECTORS : 3000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- トップテープの剥離強度：0.1N ~ 1.3N(10gf ~ 130gf)
(剥離方向は下図参照)
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 0.1N ~ 1.3N(10gf ~ 130gf)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTATION.



- 材料(MATERIAL)
キャリアテープ(CARRIER TAPE)：ポリプロピレン(POLYPROPYLENE)
トップテープ(TOPTAPE)：PET, PE, PEF
リール(REEL)：ポリスチレン(P.S) <リサイクル材を含む>
POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAINED>
- 本製品は 54548-**91 の鉛フリー(部分金メッキ)品である。
THIS PRODUCT IS LEAD FREE OF 54548-**91 (SELECTIVE GOLD).



REVISED EC NO: J2006-3468 DRAWN: HSHIMABUKURO 2006/05/17 CHECKED: KTOJO 2006/05/19 APPR: MSASAO 2006/05/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	54548-**71 DESIGN UNITS METRIC	MODEL No. THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY HSHIMABUKURO	DATE '04/02/10	TITLE 0.5 FPC CONN ZIF HSG ASSY RA BOTTOM CONTACT -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE '04/02/10			
	30 OVER	±0.3	APPROVED BY MSASAO	DATE '04/02/10	MOLEX INCORPORATED		
	ANGULAR	±3 °	MATERIAL NO. SEE CHART	DOCUMENT NO. SD-54548-040			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

10 9 8 7 6 5 4 3 2 1

F

E

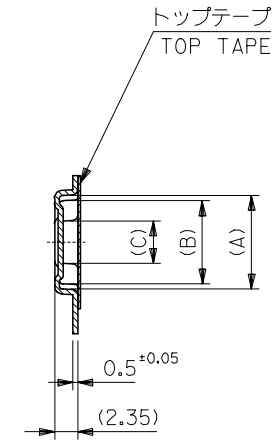
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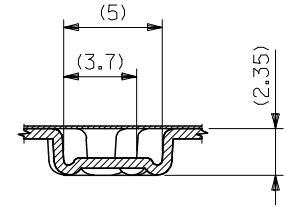
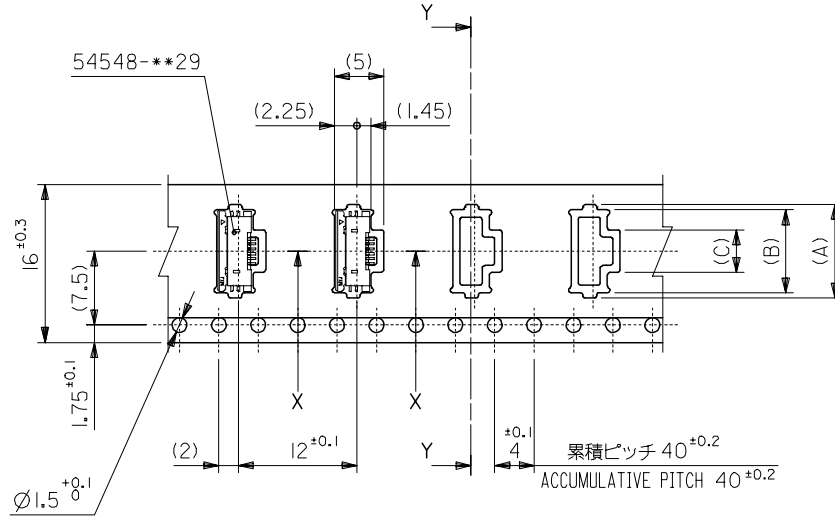
B

A

引き出し方向
PULL OUT DIRECTION



SECT. Y-Y



SECT. X-X

16mm幅キャリアテープ
16mm WIDTH CARRIER TAPE

16	21.4	17.4	4.3	8.4	9.5	54548-0671	6
			3.8	7.9	9.0	54548-0571	5
			3.3	7.4	8.5	54548-0471	4
キャリアテープ幅 CARRIER TAPE WIDTH			E	D	(C)	(B)	(A)
						製品番号 MATERIAL No.	極数 Ck+

REVISED EC NO: J2006-3468 DRW: MNABEI 2006/05/17 CHK: KTOYODA 2006/05/19 APPR: NUKITA 2006/05/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY HSHIMABUKURO	DATE '04/02/10	TITLE 0.5 FPC CONN ZIF HSG ASSY RA BOTTOM CONTACT -LEAD FREE- MOLEX INCORPORATED		
	10 OVER 30 UNDER	± 0.25	CHECKED BY KTOJO	DATE '04/02/10			
	30 OVER	± 0.3	APPROVED BY MSASAO	DATE '04/02/10			
	ANGULAR ± 3 °		MATERIAL NO.		DOCUMENT NO.	SHEET NO.	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-54548-040	2 OF 4		

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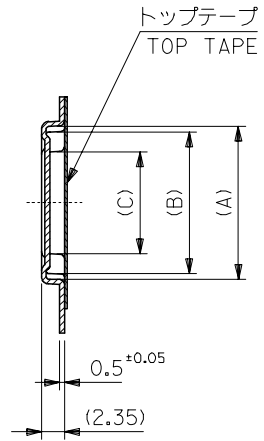
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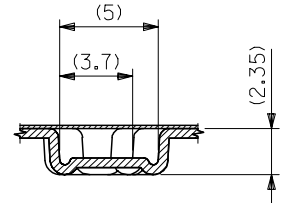
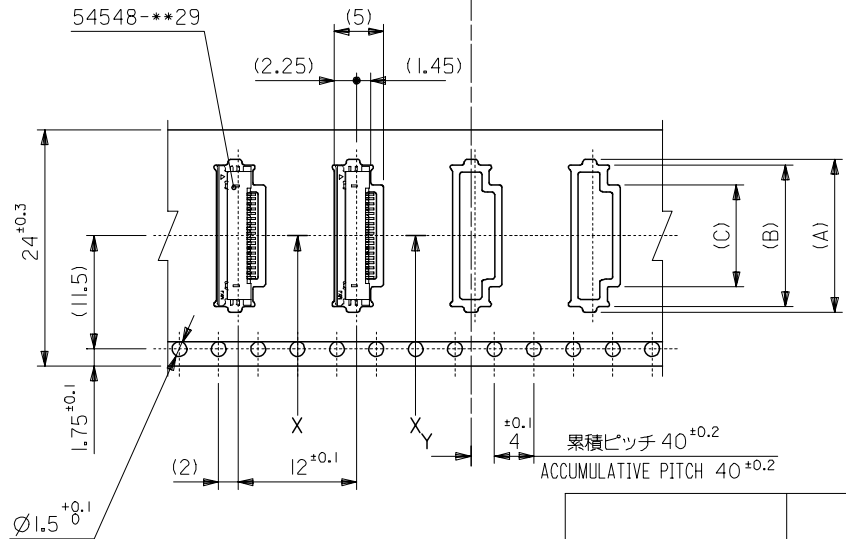
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10 9 8 7 6 5 4 3 2 1

引き出し方向
PULL OUT DIRECTION



SECT. Y-Y



SECT. X-X

24mm幅キャリアテープ
24mm WIDTH CARRIER TAPE

24	29.4	25.4	12.3	16.4	17.5	54548-2271	22		
			11.8	15.9	17.0	54548-2171	21		
			11.3	15.4	16.5	54548-2071	20		
			10.8	14.9	16.0	54548-1971	19		
			10.3	14.4	15.5	54548-1871	18		
			9.8	13.9	15.0	54548-1771	17		
			9.3	13.4	14.5	54548-1671	16		
			8.8	12.9	14.0	54548-1571	15		
			8.3	12.4	13.5	54548-1471	14		
			7.8	11.9	13.0	54548-1371	13		
			7.3	11.4	12.5	54548-1271	12		
			6.8	10.9	12.0	54548-1171	11		
			6.3	10.4	11.5	54548-1071	10		
			5.8	9.9	11.0	54548-0971	9		
5.3	9.4	10.5	54548-0871	8					
4.8	8.9	10.0	54548-0771	7					
キャリアテープ幅 CARRIER TAPE WIDTH			E	D	(C)	(B)	(A)	製品番号 MATERIAL No.	極数 Ck+

REVISED EC NO: J2006-3468 DRW: NABEI 2006/05/17 CHK: KTOYODA 2006/05/19 APPR: NUKITA 2006/05/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	10 UNDER	± 0.2	DRAWN BY HSHIMABUKURO	DATE '04/02/10	TITLE 0.5 FPC CONN ZIF HSG ASSY RA BOTTOM CONTACT -LEAD FREE-				
	10 OVER 30 UNDER	± 0.25	CHECKED BY KTOJO	DATE '04/02/10	APPROVED BY MSASAO				
	30 OVER	± 0.3	APPROVED BY MSASAO		DATE '04/02/10	MOLEX INCORPORATED			
	ANGULAR	± 3 °	MATERIAL NO.		DOCUMENT NO. SD-54548-040	SHEET NO. 3 OF 4			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10 9 8 7 6 5 4 3 2 1

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E

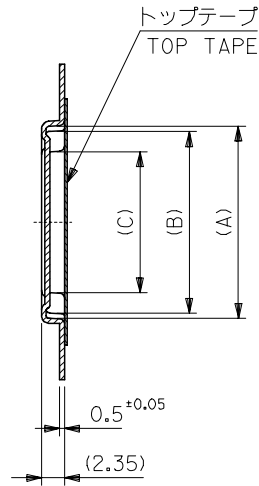
D

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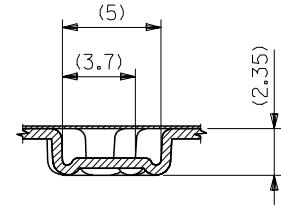
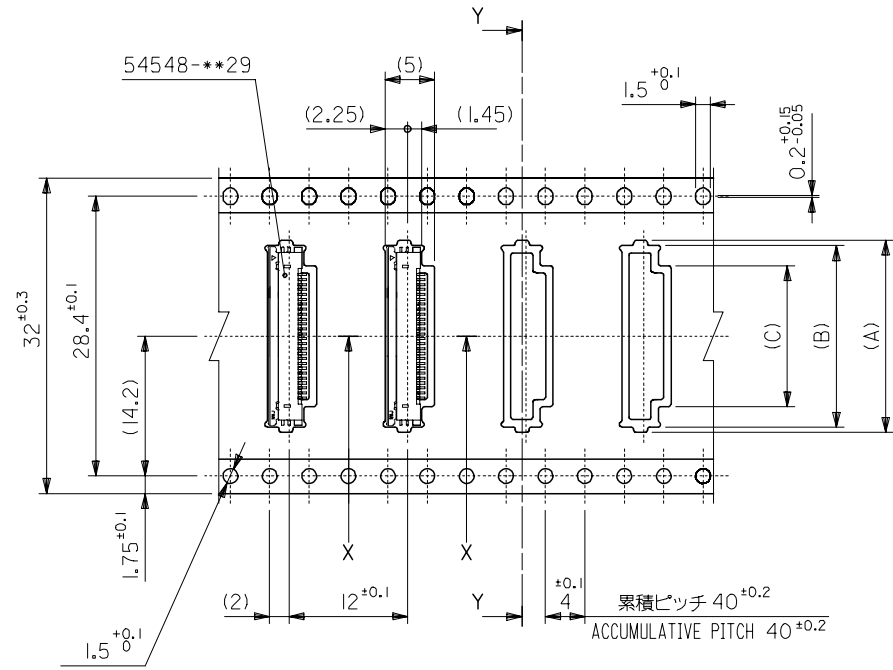
B

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引き出し方向
PULL OUT DIRECTION



SECT. Y-Y



SECT. X-X

32mm幅キャリアテープ
32mm WIDTH CARRIER TAPE

32	37.4	33.4	14.3	18.4	19.5	54548-2671	26
			13.3	17.4	18.5	54548-2471	24
			12.8	16.9	18.0	54548-2371	23
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	製品番号 MATERIAL No.	極数 Ck+

REVISED EC NO: J2006-3468 DRW: MNABEI CHK: KTOYODA APPR: NUKITA	2006/05/17 2006/05/19 2006/05/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY HSHIMABUKURO	DATE '04/02/10	TITLE 0.5 FPC CONN ZIF HSG ASSY RA BOTTOM CONTACT -LEAD FREE-			
		10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE '04/02/10	MOLEX INCORPORATED			
		30 OVER	±0.3	APPROVED BY MSASAO	DATE '04/02/10	DOCUMENT NO. SD-54548-040			
		ANGULAR	±3 °	MATERIAL NO. SEE CHART		SHEET NO. 4 OF 4			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

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